Emerging Patterning Technologies

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## Contents

### Nanoprint Lithography for High-Volume Manufacturing

- **10144 05** Nanoinprint system development for high-volume semiconductor manufacturing and the status of overlay performance *(Invited Paper)* [10144-4]
- **10144 06** Study of nanoinprint lithography (NIL) for HVM of memory devices [10144-5]
- **10144 07** Improved defectivity and particle control for nanoinprint lithography high-volume semiconductor manufacturing [10144-6]
- **10144 08** High throughput nanoinprint lithography for semiconductor memory applications [10144-7]
- **10144 09** Overlay control for nanoinprint lithography [10144-8]

### Nanoprint Masks and Applications

- **10144 0B** Selective surface smoothening of 3D micro-optical elements [10144-10]

### DSA Integration

- **10144 0E** Overview and development of EDA tools for integration of DSA into patterning solutions *(Invited Paper)* [10144-13]
- **10144 0F** Free energy modeling of block-copolymer within pillar confinements on DSA lithography [10144-14]
- **10144 0G** Process, design rule, and layout co-optimization for DSA based patterning of sub-10nm Finfet devices [10144-15]

### Direct-Write, Maskless Lithography

- **10144 0L** Simulation analysis of a miniaturized electron optics of the massively parallel electron-beam direct-write (MPEBDW) for multi-column system [10144-20]

### DSA Process and Integration: Joint Session with Conferences 10146 and 10144

- **10144 0O** Advanced surface affinity control for DSA contact hole shrink applications [10144-23]
Pattern defect reduction and LER improvement of chemo-epitaxy DSA process [10144-25]

Wide-range directed self-assembly lithography enabling wider range of applicable pattern size for both hexagonal multi-hole and line/space [10144-26]

Rules-based correction strategies setup on sub-micrometer line and space patterns for 200mm wafer scale SmartNIL™ process within an integration process flow [10144-30]

RLT uniformity improvement utilizing multi-scale NIL process simulation [10144-32]

Latest evolution in a 300mm graphoepitaxy pilot line flow for L/S applications [10144-36]

The opportunity and challenge of spin coat based nanoimprint lithography [10144-37]

Inspection and fabrication of nano-imprint stamp using electron and ion dual beam system [10144-38]

Model-based guiding pattern synthesis for on-target and robust assembly of via and contact layers using DSA [10144-39]
Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Aghili, Ali, 07
Ait-Ferhat, Dehia, 0E
Altana, Mirco, 0B
Argoud, Maxime, 00, 11
Asakawa, Koji, 0R
Asano, Masafumi, 06
Azuma, Hisanobu, 07
Bok, Cheolkyu, 12
Bos, Sandra, 0O
Brianceau, P., 0V
Cayrefourcq, Ian, 0O
Chamiot-Maitral, G., 11
Chevalier, Xavier, 00, 11
Chidambaram, Nachiappan, 0B
Cho, Changhyun, 0F
Cho, Jungbin, 12
Choi, Eun Hyuk, 06, 12
Choi, Jin, 05, 07
Choukri, M., 0V
Claveau, G., 11
Delachat, Florian, 00
Eibelhuber, M., 0V
Esashi, Masayoshi, 0L
Fenger, Germain, 0E
Fletcher, Brian, 08
Fukuhara, Kazuya, 06, 09
Gharbi, Ahmed, 0O
Granik, Yuri, 0E
Halano, Masayuki, 06
Hayashi, Tatsu, 05
Hazor, Jerôme, 0Q
Hiura, Mitsuru, 05
Hong, Hyeonson, 0F
Ida, Yasuyuki, 0Q
Ikegami, Naokatsu, 0L
Im, Ji-Young, 0X
Inanami, Ryoichi, 0X
Irving, J., W., 08
Ito, Kiyohito, 0Q
Jones, Chris E., 07
Jung, E., 0F
Jung, Wooyoun, 06, 09, 12
Kapral, Chris, 0E
Khosrau, Daman, 0E
Khusnutdinov, Niyaq, 08
Kim, Hyun-Woo, 0F
Kimura, Atsushi, 05
Kirchner, Robert, 0B
Kitano, Takahiro, 0Q
Kobayashi, Kei, 06, 12
Kobayashi, Sachiko, 0X
Kodachi, Nobuhiro, 05
Kojima, Akira, 0L
Komori, Motofumi, 0X
Kono, Takuya, 06, 09, 0X, 12
Koshiba, Nobuyoshi, 0L
Krasnova, Polina, 0E
Landis, S., 0V
Lahey, Céline, 0O
Laure, M., 0V
Lee, Kyupil, 0F
Lim, Yonghyun, 09, 12
Liu, Weijun, 08
Longsine, Whitney, 08
Ma, Yuansheng, 0E, 14
Maeda, Shimon, 0X
Matsuoka, Yoichi, 07
Mayr, M., 0V
Mishima, Kazuhiro, 05
Mitra, Joydeep, 0E, 0G, 14
Mitsuyasu, Masaki, 09
Miyaguchi, Hiroshi, 0L
Mizuno, Makoto, 07
Monget, Cédric, 0O
Motikita, Shinya, 0Q
Morita, Seiji, 0R
Morohoshi, Hiroshi, 05
Muramatsu, Makoto, 0Q
Muroyama, Masanori, 0L
Nakasugi, Tetsuro, 06, 09, 12
Nakayama, Takahiro, 07
Navarro, Christophe, 00, 11
Nicolet, Célia, 0O
Nishi, Takanori, 0Q
Okawa, Noriaki, 0Q
Pain, Laurent, 0O, 0V
Pan, David Z., 0G, 14
Park, Jemin, 0F
Park, Joosung, 0F
Park, Seokhan, 0F
Pimentel Barros, Patricia, 00, 11
Saito, Ryuichi, 0R
Saito, Yusuke, 0Q
Sasao, Noriaki, 0R
Sawabe, Tomoaki, 0R
Schiff, Helmut, 0B
Shy, Shyi-Long, 13
Stachowiak, Tim, 0B
Suda, Ryutaro, 0L
Sugimura, Shinobu, 0R
Suzaki, Yoshio, 05
Suzuki, Masato, 06, 09
Takabayashi, Yukio, 05, 07
Teyssedre, H., 0V
Thanner, C., 0V
Ting, Yung-Chiang, 13
Tiron, Raluca, 00, 11
Tobana, Toshikatsu, 0Q
Tokue, Hiroshi, 06
Torres, J. Andres, 0E, 0G, 14
Totsu, Kentaro, 0L
Traub, Matthew, 08
Tsuda, Hirotaka, 0X
Tsujii, Masatoshi, 12
Washida, Kazuhiro, 0X
Wimplinger, M., 0V
Yamamoto, Ryosuke, 0R
Yamashita, Kyoji, 0X
Ye, Zhengmao, 08
Yonekawa, Masami, 07
Yoshida, Shinya, 0L
Yoshida, Takahiro, 05
Yoshida, Takashi, 0L
You, Gen, 0Q
Zhang, Wei, 08
Zorbach, W., 0V
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3 Nanoprint Masks and Applications
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Helmut Schift, Paul Scherrer Institut (Switzerland)

4 DSA Integration
James A. Liddle, National Institute of Standards and Technology
(United States)
Hsinyu Tsai, IBM Thomas J. Watson Research Center (United States)

5 Direct-Write, Maskless Lithography
Ines A. Stolberg, Vistec Electron Beam GmbH (Germany)
Marco Wieland, MAPPER Lithography (Netherlands)

6 DSA Process and Integration: Joint Session with Conferences 10146
and 10144
Ralph R. Dammel, EMD Performance Materials Corporation
(United States)
Chi-Chun Liu, IBM Corporation (United States)

7 DSA Materials and Processes: Joint Session with Conferences 10146
and 10144
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